

Through Silicon Via (TSV) Packaging Market, Global Outlook and Forecast 2022-2028

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Abstracts

Through Silicon Via (TSV) packaging technology enables homogenous and heterogeneous integration of logic and memory co-located closely together in a small form-factor assembly.

This report contains market size and forecasts of Through Silicon Via (TSV) Packaging in Global, including the following market information:

Global Through Silicon Via (TSV) Packaging Market Revenue, 2017-2022, 2023-2028, (\$ millions)

Global top five companies in 2021 (%)

The global Through Silicon Via (TSV) Packaging market was valued at million in 2021 and is projected to reach US\$ million by 2028, at a CAGR of % during the forecast period.

The U.S. Market is Estimated at \$ Million in 2021, While China is Forecast to Reach \$ Million by 2028.

2.5D Segment to Reach \$ Million by 2028, with a % CAGR in next six years.

The global key manufacturers of Through Silicon Via (TSV) Packaging include Applied Materials, STATS ChipPAC Ltd, Micralyne, Inc, Teledyne, DuPont, China Wafer Level CSP Co, Samsung Electronics, Amkor Technology and FRT GmbH. etc. In 2021, the global top five players have a share approximately % in terms of revenue.

MARKET MONITOR GLOBAL, INC (MMG) has surveyed the Through Silicon Via (TSV) Packaging companies, and industry experts on this industry, involving the revenue, demand, product type, recent developments and plans, industry trends, drivers, challenges, obstacles, and potential risks.

Total Market by Segment:

Global Through Silicon Via (TSV) Packaging Market, by Type, 2017-2022, 2023-2028 (\$ millions)

Global Through Silicon Via (TSV) Packaging Market Segment Percentages, by Type, 2021 (%)

2.5D

3D

Global Through Silicon Via (TSV) Packaging Market, by Application, 2017-2022, 2023-2028 (\$ millions)

Global Through Silicon Via (TSV) Packaging Market Segment Percentages, by Application, 2021 (%)

Memory Arrays

Image Sensors

Graphics Chips

MPUs (Microprocessor Units)

DRAM (Dynamic Random Access Memory)

Integrated Circuits

Others

Global Through Silicon Via (TSV) Packaging Market, By Region and Country,
2017-2022, 2023-2028 (\$ Millions)

Global Through Silicon Via (TSV) Packaging Market Segment Percentages, By Region
and Country, 2021 (%)

North America

US

Canada

Mexico

Europe

Germany

France

U.K.

Italy

Russia

Nordic Countries

Benelux

Rest of Europe

Asia

China

Japan

South Korea

Southeast Asia

India

Rest of Asia

South America

Brazil

Argentina

Rest of South America

Middle East & Africa

Turkey

Israel

Saudi Arabia

UAE

Rest of Middle East & Africa

Competitor Analysis

The report also provides analysis of leading market participants including:

Key companies Through Silicon Via (TSV) Packaging revenues in global market, 2017-2022 (estimated), (\$ millions)

Key companies Through Silicon Via (TSV) Packaging revenues share in global market, 2021 (%)

Further, the report presents profiles of competitors in the market, key players include:

Applied Materials

STATS ChipPAC Ltd

Micralyne, Inc

Teledyne

DuPont

China Wafer Level CSP Co

Samsung Electronics

Amkor Technology

FRT GmbH

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